# Product End-of-Life Disassembly Instructions

## Product Category: Monitors and Displays

### Marketing Name / Model

[List multiple models if applicable.]

- HP ZR2740w 27-inch LED Backlit IPS Monitor
- Name / Model #2
- Name / Model #3
- Name / Model #4
- Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
refractory ceramic fibers

Components, parts and materials containing radioactive substances 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Hand</td>
<td></td>
</tr>
<tr>
<td>Description #2 Slotted Screwdriver</td>
<td></td>
</tr>
<tr>
<td>Description #3 Philips Screwdriver</td>
<td></td>
</tr>
<tr>
<td>Description #4 Hex Socket Screwdriver</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Please refer to the attached file for disassembly process
2. Remove the four screws from bucket
3. Open front cover
4. Be careful the line, and remove the three screws from keyboard
5. Remove all the tapes from main bracket
6. Remove the screws from left and right side of the bracket
7. Pressure LVDS connector on both sides and pull out
8. Remove the screws from DVI connector
9. Remove the screws from main board and converter board
10.
11.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Method of LED disassembly on 27W

1. Method of disassembly on LM270WQ1-SDDA
Method of LED disassembly on LM270WQ1-SDDA

Bare LCM

Step 1: Remove the Screw (4ea) Source PCB

Step 2: Remove the Cover Shield

Step 3: Dismantle the FFC Connector (2ea)

Step 4: Separate Control PCB

Step 5: Dismantle the Case Top (Down)

Step 6: Remove the ITO Tape (2ea)

Step 7: Separate Board Ass’y

Step 9: Remove the Guide panel screw (6ea)
Method of LED disassembly on LM270WQ1-SDDA

Step 10: Dissemble the Guide panel

Step 11: Remove the Sheet

Step 12: Remove the LGP

Step 13: Remove the reflector

Step 14: Remove the guide light screw (2ea)

Step 15: Remove the tape (2ea)

Step 16: Remove the tape

Step 17: Remove the Black tape

Step 18: Separate light guide (Back)
Method of LED disassembly on LM270WQ1-SDDA

Step 19: Separate light guide (Front)

Separated

Step 20: Remove the LED wire Assy

Separation

Step 21: Remove the LED bar Screw

Step 22: Separate the LED bar

Disassembled
ZR2740 ME disassembly instruction photos

Tatung ME team
3/28/11’

J.k.Liao
Remove the four screws form bucket
Open the front cover
Be careful the line, and remove the three screws from keyboard.
Remove all the tapes from main bracket.
Remove these three tapes from main bracket.
Remove the screws from left and right side.
Pressure on both sides, then pull out.
Remove the screws from connector.
Remove the screws from board.
Remove the screws from board.